



Material Content Data Sheet



Sales Product Name		BFP 196 E6327		Issued		29. August 2013		
MA#		MA000787166						
Package		PG-SOT143-4-2		Weight*		11.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.03		260	
	non noble metal	tin	7440-31-5	0.001	0.01		67	
	inorganic material	silicon	7440-21-3	0.025	0.23	0.27	2265	2592
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		77	
	non noble metal	titanium	7440-32-6	0.004	0.04		387	
	non noble metal	chromium	7440-47-3	0.013	0.12		1160	
	non noble metal	copper	7440-50-8	4.310	38.51	38.68	385063	386687
wire	noble metal	gold	7440-57-5	0.009	0.08	0.08	842	842
encapsulation	organic material	carbon black	1333-86-4	0.105	0.94		9392	
	inorganic material	antimonytrioxide	1309-64-4	0.158	1.41		14088	
	plastics	brominated resin	-	0.197	1.76		17610	
	plastics	epoxy resin	-	1.643	14.68		146752	
	inorganic material	silicondioxide	60676-86-0	4.468	39.89	58.68	399165	587007
leadfinish	non noble metal	tin	7440-31-5	0.217	1.94	1.94	19350	19350
plating	noble metal	silver	7440-22-4	0.039	0.35	0.35	3522	3522
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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